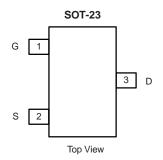
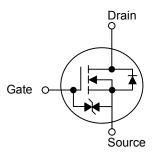




N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}$ (Ω)	I _D (mA)				
60	2 at V _{GS} = 10 V	300				





FEATURES

Low On-Resistance: 2 Ω
Low Threshold: 2 V (typ.)

Low Input Capacitance: 25 pF

• Fast Switching Speed: 25 ns

Low Input and Output Leakage

• DT-Trench Power MOSFET

1200V ESD Protection

Compliant to RoHS Directive 2002/95/EC

BENEFITS

- · Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

APPLICATIONS

- · Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- · Battery Operated Systems
- Solid-State Relays

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted									
Parameter	Symbol	Limit	Unit						
Drain-Source Voltage		V_{DS}	60	V					
Gate-Source Voltage		V_{GS}	± 20						
Continuous Drain Current (T,I = 150 °C) ^b	T _A = 25 °C	- I _D	300	mA					
Continuous Drain Current (1 _J = 150°C)	T _A = 100 °C		190						
Pulsed Drain Current ^a		I _{DM}	800	İ					
Davias Diagin estimati	T _A = 25 °C	P _D	0.35	W					
Power Dissipation ^b	T _A = 100 °C	ı D	0.14	VV					
Maximum Junction-to-Ambient ^b		R _{thJA}	350	°C/W					
Operating Junction and Storage Temperature Range		$T_{J_{i}}T_{stg}$	- 55 to 150	°C					

Notes

- a. Pulse width limited by maximum junction temperature.
- b. Surface Mounted on FR4 board.

RoHS

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



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SPECIFICATIONS $T_A = 25 ^{\circ}C$	Symbol	Test Conditions	Limits			
			Min.	Typ. ^a	Max.	Unit
Static						ı
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 10 \mu\text{A}$	60			2.5 V
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		2.5	
Gate-Body Leakage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 10	μА
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 15 \text{ V}$			1	
	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$			± 150	nA
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			± 1000	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 100	
Zero Gate Voltage Drain Current		V _{DS} = 60 V, V _{GS} = 0 V			1	μA
	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V , T _J = 125 °C			500	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V, V _{DS} = 7.5 V	800			mA
		V _{GS} = 4.5 V, V _{DS} = 10 V	500			
Drain-Source On-Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 500 mA			2	Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 200 \text{ mA}$			4	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 200 mA	100			mS
Diode Forward Voltage	V _{SD}	$I_S = 200 \text{ mA}, V_{GS} = 0 \text{ V}$			1.3	V
Dynamic ^a			·!			
Total Gate Charge	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_{D} \cong 250 \text{ mA}$		0.4	0.6	nC
Input Capacitance	C _{iss}	.,		30		pF
Output Capacitance	C _{oss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$ f = 1 MHz		6		
Reverse Transfer Capacitance	C _{rss}	I = I IVIDZ		2.5		
Switching ^{a, b, c}				•	•	
Turn-On Time	t _{d(on)}	$V_{DD} = 30 \text{ V, R}_{L} = 150 \Omega$			25	ns
Turn-Off Time	t _{d(off)}	$I_D \cong 200 \text{ mA}, V_{GEN} = 10 \text{ V}, R_G = 10 \Omega$			35	

Notes:

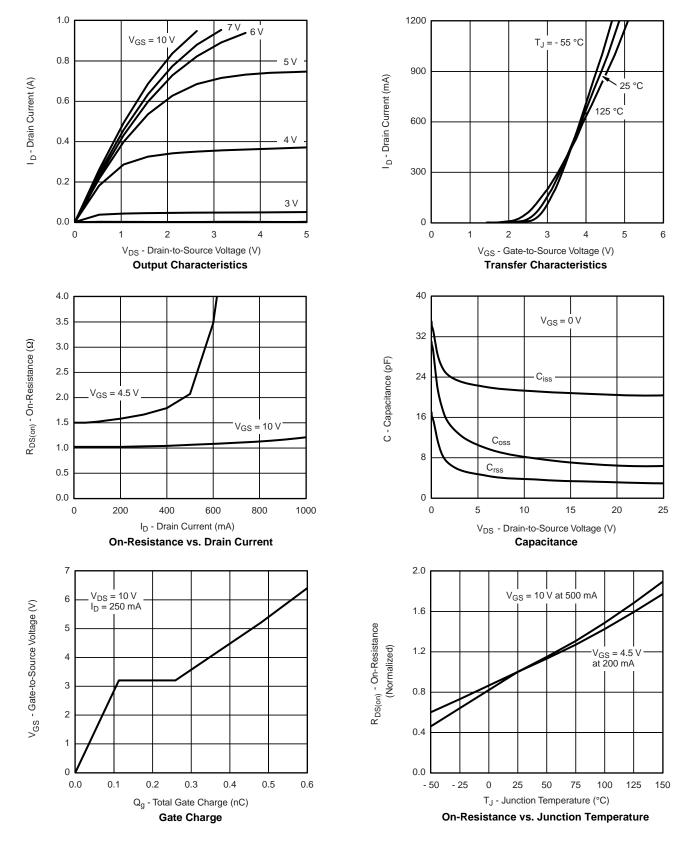
- a. For DESIGN AID ONLY, not subject to production testing. b. Pulse test: PW \leq 300 μ s duty cycle \leq 2 %.
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



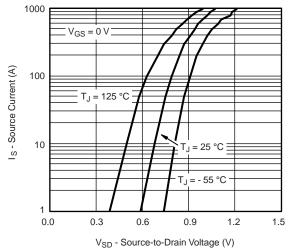


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

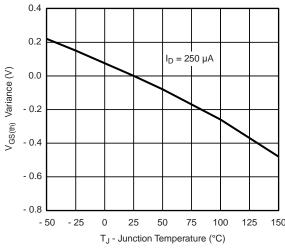




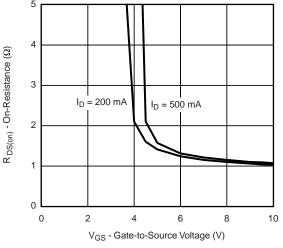
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



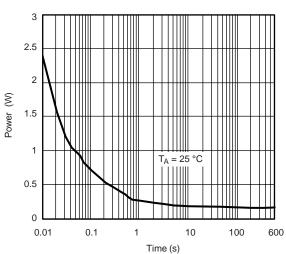
Source-Drain Diode Forward Voltage



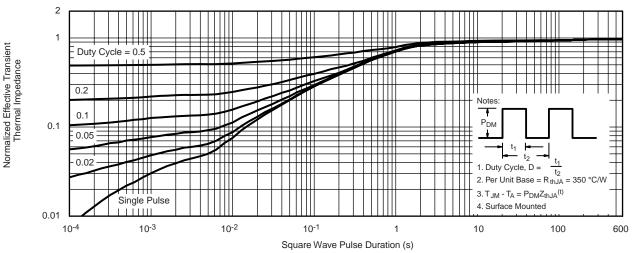
Threshold Voltage Variance Over Temperature



On-Resistance vs. Gate-Source Voltage



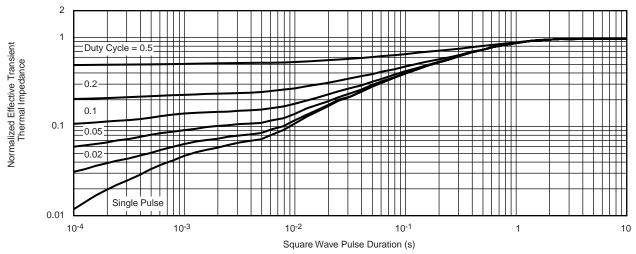
Single Pulse Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Foot

Note

- · The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.





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